

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT5312770

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	TOMOHIRO KITANO	01/07/2019
RECEIVING PARTY DATA		
Name:	MICRON TECHNOLOGY, INC.	
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City:	BOISE	
State/Country:	IDAHO	
Postal Code:	83716-9632	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	16235645
CORRESPONDENCE DATA		
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
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ATTORNEY DOCKET NUMBER:	P279338US01	
NAME OF SUBMITTER:	DENISE SHERIDAN	
SIGNATURE:	/Denise Sheridan/	
DATE SIGNED:	01/07/2019	
Total Attachments: 2		
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Tomohiro Kitano

Serial No.: 16/235,645

Filed: December 28, 2018

For : APPARATUSES AND METHODS
FOR ARRANGING THROUGH-
SILICON VIAS AND PADS IN A
SEMICONDUCTOR DEVICE

Docket No. P279338.US.01

Disclosure No. 2018-1347.00/US

ASSIGNMENT:

 X Enclosed for recording
 Previously recorded

Date:

Reel:

FOR GOOD AND VALUABLE CONSIDERATION, the receipt, sufficiency and adequacy of which are hereby acknowledged, the undersigned does hereby:

SELL, ASSIGN AND TRANSFER to **Micron Technology, Inc.** (the "Assignee"), a corporation of Delaware, having a place of business at 8000 South Federal Way, Boise, Idaho 83716-9632, the entire right, title and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which was filed on December 28, 2018, and assigned Application No. 16/235,645 and is titled "**APPARATUSES AND METHODS FOR ARRANGING THROUGH-SILICON VIAS AND PADS IN A SEMICONDUCTOR DEVICE**"; such application and all divisional, continuing, substitute, renewal, reissue and all other applications for patent which have been or shall be filed in the United States and all foreign countries on any of such improvements; all original and reissued patents which have been or shall be issued in the United States and all foreign countries on such improvements; and specifically including the right to file foreign applications under the provisions of any convention or treaty and claim priority based on such application in the United States of America;

AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign patents granted on such improvements to the Assignee;

WARRANT AND COVENANT that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by the undersigned, and that the full right to convey the same as herein expressed is possessed by the undersigned;

COVENANT that, when requested and at the expense of the Assignee, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all such improvements; execute all rightful oaths, declarations, assignments, powers of attorney and other papers; communicate to the Assignee all facts known to the undersigned relating to such improvements and the history thereof; and generally do everything possible which the Assignee shall consider desirable for securing, maintaining and enforcing proper patent protection for such improvements and for vesting title to such improvements in the Assignee;

TO BE BINDING on the heirs, assigns, representatives and successors of the undersigned and extend to the successors, assigns and nominees of the Assignee.

Signature: 北野 知宏

Date: 1 / 7 / 2019

Assignor Name: Tomohiro Kitano

Witness # 1:

Signature: Masayoshi Yamazaki

Date: 1 / 7 / 2019

Witness Name: Masayoshi Yamazaki

Witness # 2:

Signature: Shoko Tomita

Date: 01-07-2019

Witness Name: Shoko Tomita